



RoHS & Halogen Free & REACH Compliance.

**SPECIFICATION FOR APPROVAL**

Customer : \_\_\_\_\_

Customer P/N : \_\_\_\_\_

Drawing No : \_\_\_\_\_

Quantity : \_\_\_\_\_ Pcs.      Date : \_\_\_\_\_

Chilisin P/N : **BTLB0020123G6H6A10**

SPECIFICATION ACCEPTED BY:	
COMPONENT ENGINEER	
ELECTRICAL ENGINEER	
MECHANICAL ENGINEER	
APPROVED	
REJECTED	

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Drawn by <b>YW</b>	Checked by <b>CF</b>	Approved by <b>Derek</b>
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ISO9001 ISO14001 IATF16949 CHILISIN ELECTRONICS CORP.

## APPLICATION

WLAN, Bluetooth, Home RF.

## FEATURES

### 1-1 Compact Size

Miniaturized SMD packaged in low profile and lightweight.

### 1-2 Low loss

Low insertion loss, high attenuation.

### 1-3 High Soldering Heat Resistance

High quality termination allows both flow and re-flow soldering methods to be applied.

### 1-4 Characteristics

Eliminate noise over a wide frequency range. Idea for high frequency and space limited designs.

### 1-5 Internal Shielding incorporated

### 1-6 Available in tape and reel packaging for automatic mounting

## PRODUCT IDENTIFICATION

B T L B 0 0 2 0 1 2 ###xx A 1 0  
 ①            ②            ③            ④            ⑤    ⑥

- ① Product Code
- ② Customer Code
- ③ Dimension Code
- ④ Series Type (### represents center frequency and xx represents material type)
- ⑤ Design Code
- ⑥ Version Code

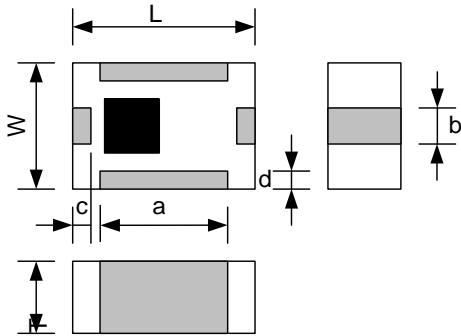
## ELECTRICAL REQUIREMENTS

Part NO.	Pass Band	Insertion Loss in BW	VSWR In BW	Attenuation
BTLB0020123G6H6A10	3300~3900 MHz	1.8 dB max.	2 max.	15 dB min. at 100~2600 MHz 20 dB min. at 6000~9000 MHz

Operating Temperature Range : -40~85°C

Power Capacity : 3W max.

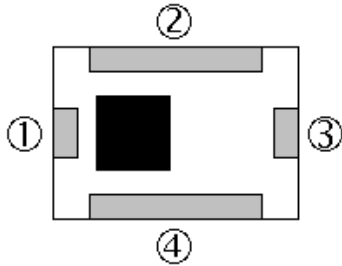
## PRODUCT DIMENSION



L	W	T	a
2.00±0.15	1.25±0.15	0.95±0.10	1.60+0.10 -0.15
b	c	d	
0.30+0.10 -0.15	0.30±0.20	0.30±0.20	

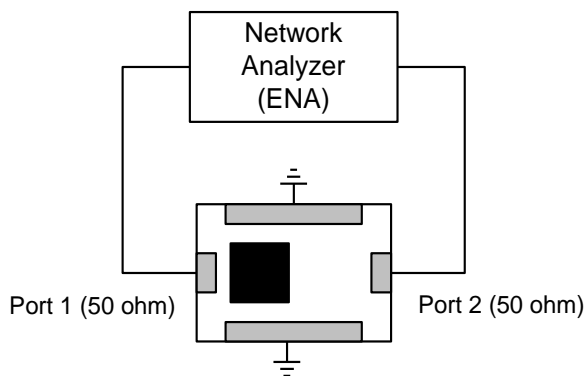
NOTE : Dimensions in mm

## TERMINAL CONFIGURATION



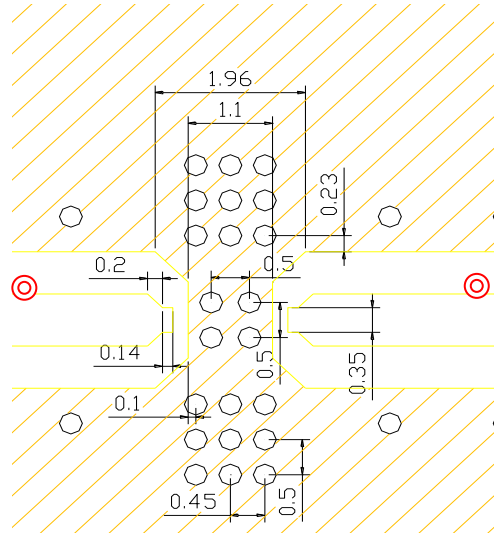
- ① IN
- ② GND
- ③ OUT
- ④ GND

## MEASURING DIAGRAM



Test Instrument :  
Agilent E5071A Network Analyzer

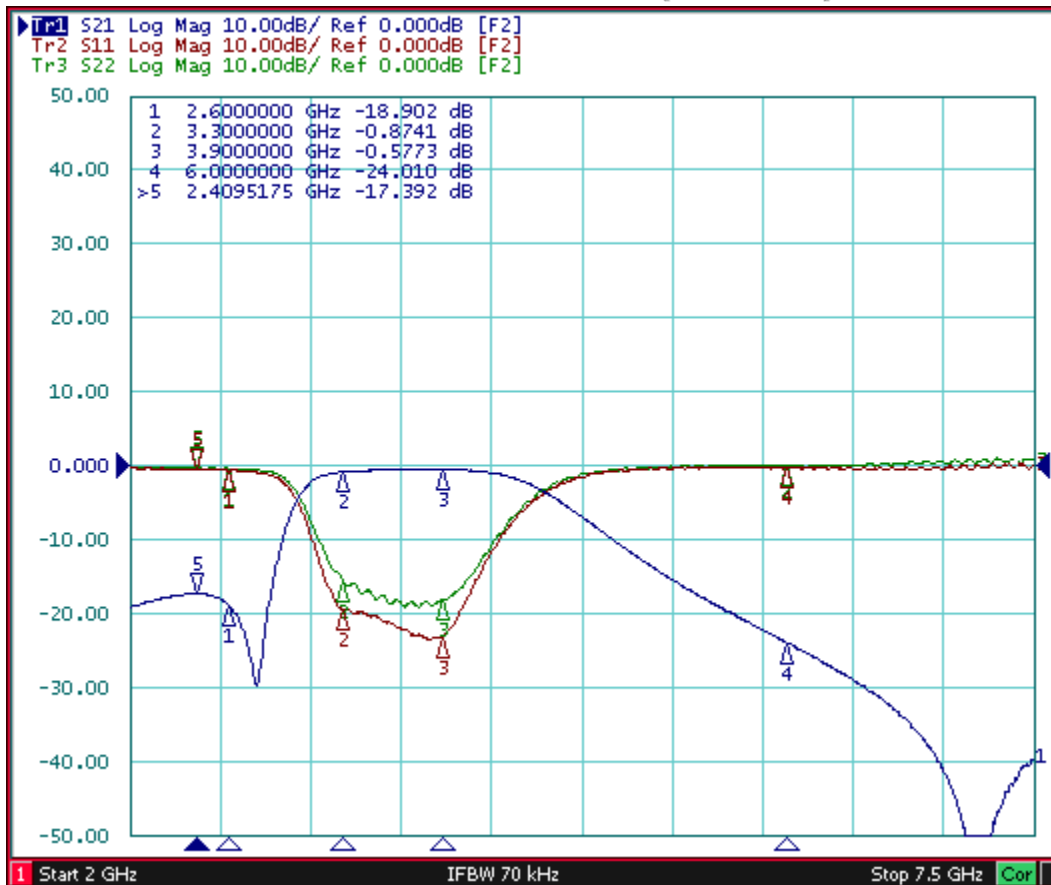
## RECOMMENDED PCB LAYOUT



Unit : mm

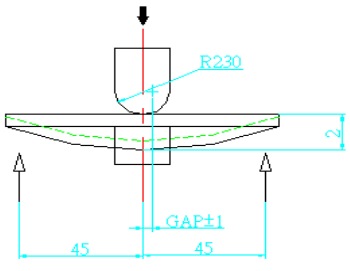
- ⊙ Line width should be designed to match 50Ω characteristic impedance, depending on PCB material and thickness.

## ELECTRICAL CHARACTERISTICS ( T=25°C )



## RELIABILITY TEST

### Mechanical Test

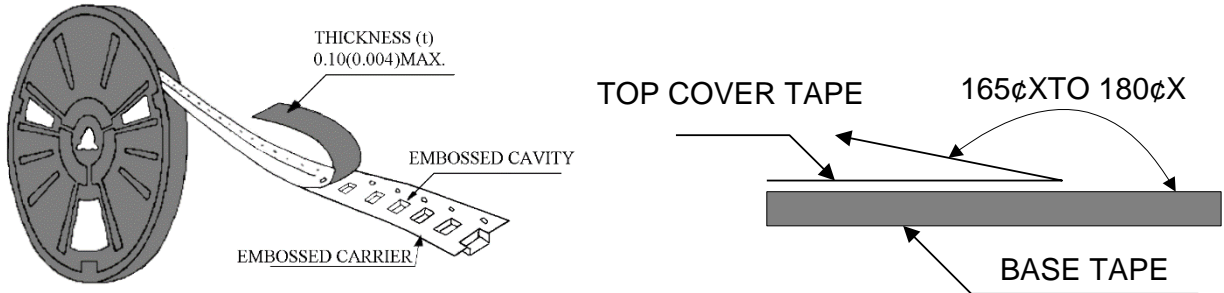
Item	Test Condition	Specification
<b>Vibration</b>	10 Hz/min~55 Hz/min~10 Hz/min vibration frequency with 1.5 mm amplitude for two hours in x, y, z directions	No apparent damage
<b>Drop shock</b>	Dropped onto printed circuit board from 100cm height three times in x, y, z directions. The terminals shall be protected.	No apparent damage
<b>Soldering heat resistance</b>	Preheating temperature : $150\pm 10^{\circ}\text{C}$ Preheating time : 1 to 2 minutes Solder bath temperature : $260\pm 5^{\circ}\text{C}$ Bathing time : $5\pm 0.5$ seconds	No apparent damage
<b>Bending test onto printed circuit board</b>	<p>Solder specimen LTCC components on the test printed circuit board (L: 100 x W: 40 x T: 1.6mm) in appended recommended PCB pattern.</p> <p>Apply the load in direction of the arrow until bending reaches 2 mm.</p>  <p style="text-align: right;">Unit: mm</p>	No apparent damage
<b>Solderability</b>	The dipped surface of the terminal shall be at least 75% covered with solder after dipped in solder bath of $245\pm 5^{\circ}\text{C}$ for $3\pm 0.5$ seconds.	No apparent damage

### Environment Test

<b>Thermal shock</b>	$-40^{\circ}\text{C}$ ~ $85^{\circ}\text{C}$ for 100 cycles each cycle being 30 min	No apparent damage Fulfill the electrical spec. after test
<b>Humidity resistance</b>	$85\pm 2^{\circ}\text{C}$ , 80~90% R.H. for 500 hours	No apparent damage Fulfill the electrical spec. after test
<b>High temperature resistance</b>	$85\pm 2^{\circ}\text{C}$ for 500 hours	No apparent damage Fulfill the electrical spec. after test
<b>Low temperature resistance</b>	$-40\pm 3^{\circ}\text{C}$ for 500 hours	No apparent damage Fulfill the electrical spec. after test

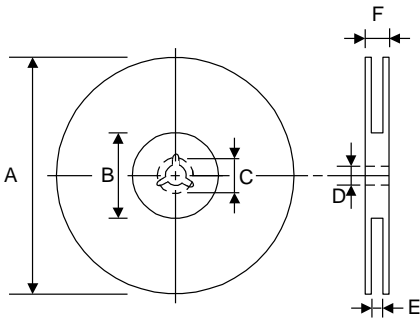
## PACKAGING FOR SMC

### Peel-off force



The force for peeling off cover tape is 10 grams in the arrow direction.

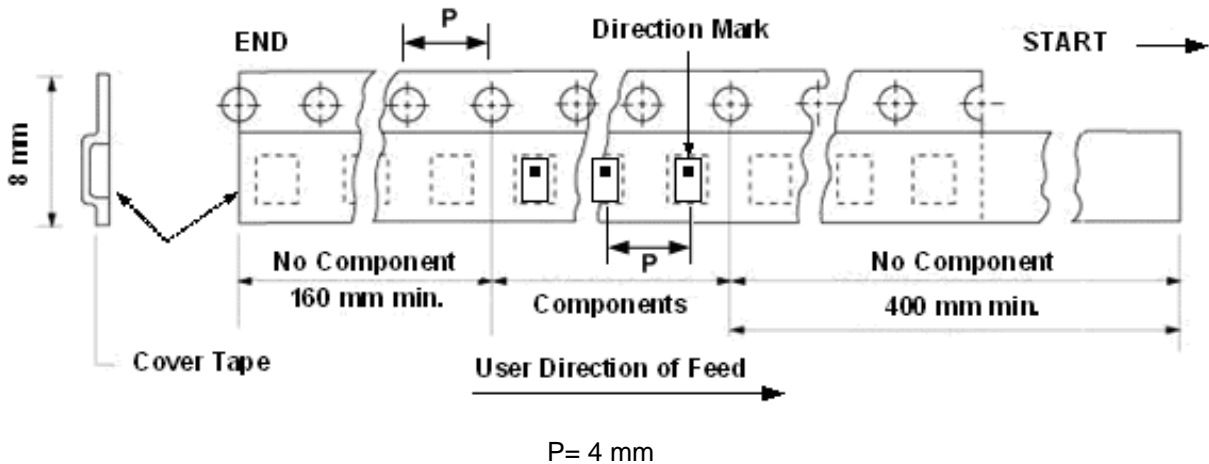
### Dimension (Unit: mm)



TYPE	A	B	C	D	E	F
8 mm	178±1	60+0.5 -0	-	13±0.2	9±0.5	12±0.5
12 mm	178±0.3	60±0.2	19.3±0.1	13.5±0.1	13.6±0.1	-

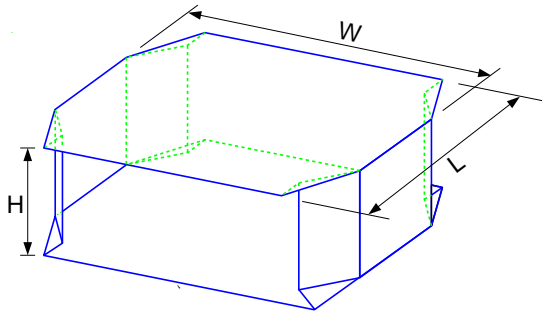
### Taping quantity

SERIES	5824 5724	5320 5220	4532	4516	3225	3216 2520	2012 1608 1109	1005
PCS/Reel	5000	3000	1000	2000	2500	3000	4000	10000



## TAPE PACKING CASE

Unit:cm



No. of Reels	W	L	H
2	18±0.5	18±0.5	2.4±0.2
3	18±0.5	18±0.5	3.6±0.2
4	18±0.5	18±0.5	4.8±0.2
5	18±0.5	18±0.5	6.0±0.2

## OPERATION TEMPERATURE

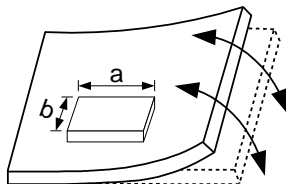
-40°C~85°C

## STORAGE CONDITION

The temperature should be within -40~85°C and humidity should be less than 75% RH. The product should be used within 6 months from the time of delivery.

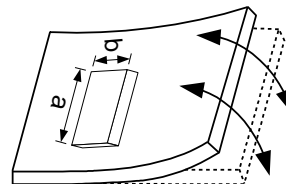
## ATTENTION REGARDING PCB BENDING

- (a) PCB shall be designed so that products are not subjected to the mechanical stress for board wrapage. Product shall be located in the sideways direction to the mechanical stress.



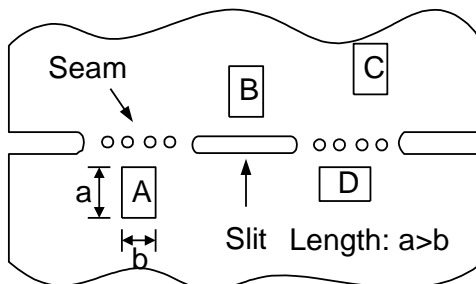
(Poor example)

Length:  $a > b$

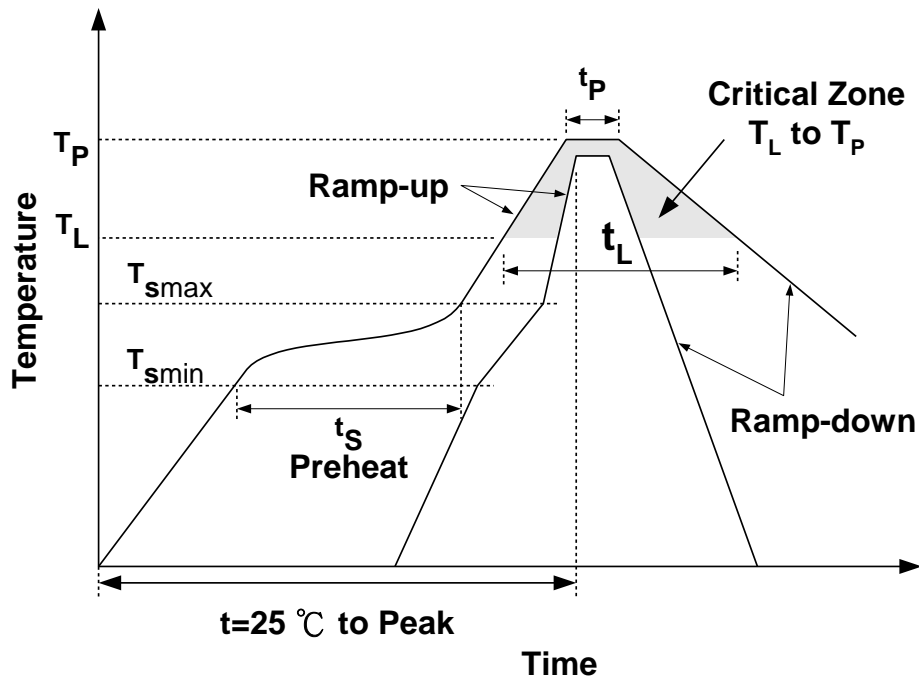


(Good example)

- (b) Products (A,B,C,D) shall be located carefully so that products are not subjected to the mechanical stress due to warping the board. Because they may be subjected to the mechanical stress in order of  $A > C > B \approx D$ .



## RECOMMENDED REFLOW SOLDERING PROFILE



Profile Feature		Sn-Pb	Pb-Free
Preheat	$t_s$	60~120 seconds	60~180 seconds
	$T_{smin}$	100°C	150°C
	$T_{smax}$	150°C	200°C
Average ramp-up rate ( $T_{smax}$ to $T_P$ )		3°C/second max.	3°C/second max.
Time main above	Temperature ( $T_L$ )	183°C	217°C
	Time ( $t_L$ )	60~150 seconds	60~150 seconds
Peak temperature ( $T_P$ )		230°C	250~260°C
Time within 5°C of actual peak temperature ( $t_P$ )		10 seconds	10 seconds
Ramp-down rate		6°C/sec max.	6°C/sec max.
Time 25°C to peak temperature		6 minutes max.	8 minutes max.

### NOTES

The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.